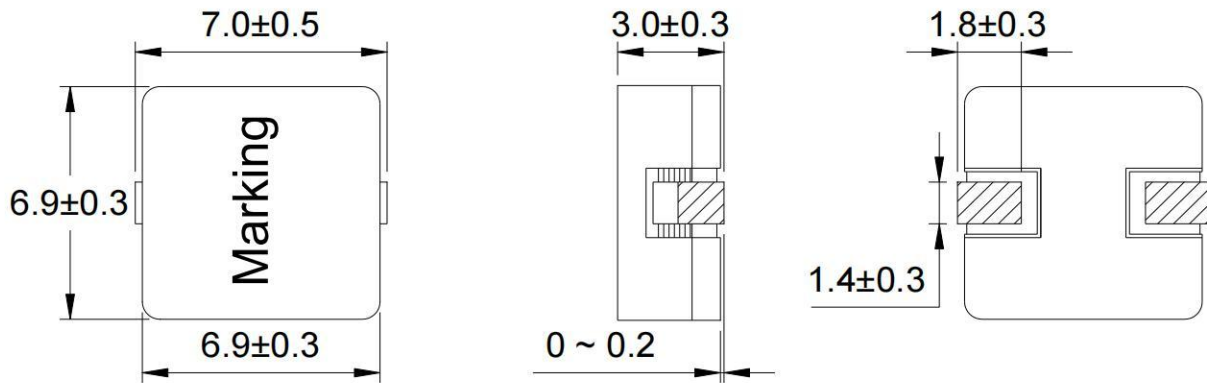


Outline: 产品概要

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI)
磁屏蔽结构：抗电磁干扰(EMI)性能强
- Flat wire winding, achieve a low D.C. Resistance.
扁平线绕组，实现极低的直流电阻。
- Low loss, high efficiency, wide application frequency and application scope.
低损耗，高效率，应用频率宽，适用范围广。
- Lightweight design, save space, suitable for high density SMT.
轻薄型设计，节省空间，适合高密度贴装。
- Operating temperature : -55°C ~ +150°C (Including coil's temperature rise)
工作温度：-55°C ~ +150°C (包含线圈发热)

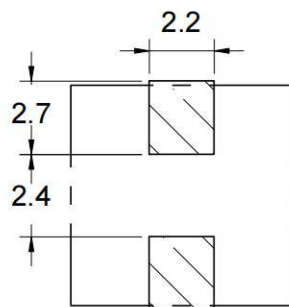
1 Appearance and Dimensions (mm) 外形尺寸 (mm)



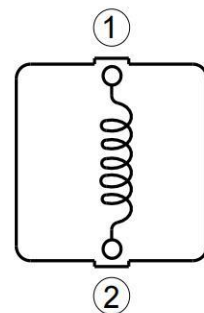
2 Marking 印字标识



3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



4 Schematic 原理图





5 Electrical Characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 $\times 1$ $\pm 20\%$	D.C.R. ($\text{m}\Omega$) 直流电阻		Saturation current (A) 饱和电流 $\times 2$ Typical	Temperature rise current (A) 温升电流 $\times 3$ Typical
		Typical	Max		
YZBX0630-R10M	0.10	0.78	0.90	70.0	23.0
YZBX0630-R22M	0.22	1.58	1.82	48.0	19.0
YZBX0630-R47M	0.47	3.40	3.91	34.0	14.5
YZBX0630-1R0M	1.00	5.63	6.50	18.5	11.5
YZBX0630-1R5M	1.50	7.90	9.10	15.0	8.70
YZBX0630-2R2M	2.20	10.8	12.4	12.0	7.80

- All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C 条件下测试。

- ※1 Inductance measure condition at 100kHz, 0.5V.

电感测试条件为 100kHz, 0.5V。

- ※2 Saturation current : the actual value of DC current when the inductance decrease 30% of its initial value.

饱和电流：电感值下降其初始值的 30% 时所加载的实际直流电流值。

- ※3 Temperature rise current : the actual value of DC current when the temperature rise is $\Delta T 50^\circ\text{C}$ ($T_a = 25^\circ\text{C}$).

温升电流：使产品温度上升到 $\Delta T 50^\circ\text{C}$ 时所加载的实际直流电流值 ($T_a = 25^\circ\text{C}$)。

- ※ Special remind : Circuit design, component placement, PCB size and thickness, cooling system and etc.

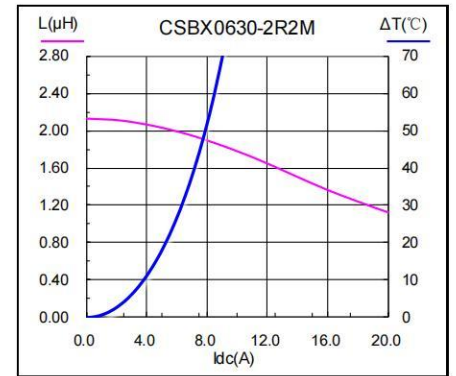
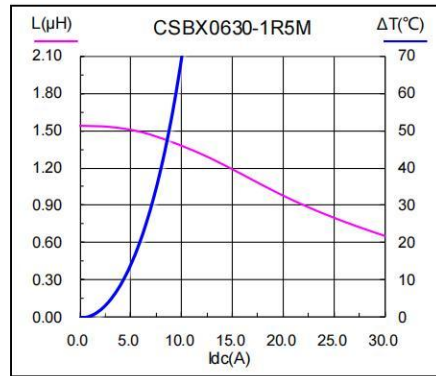
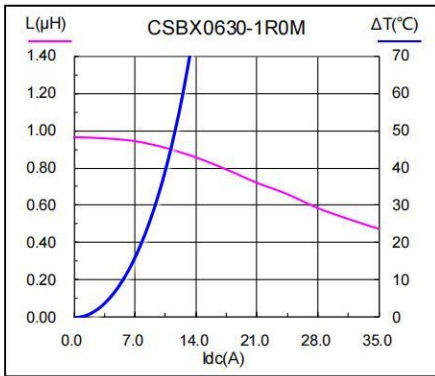
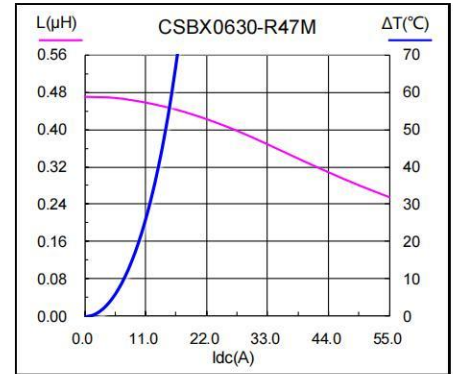
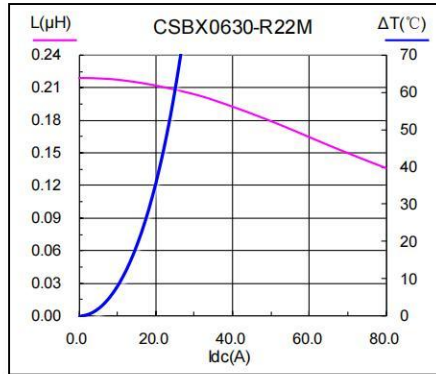
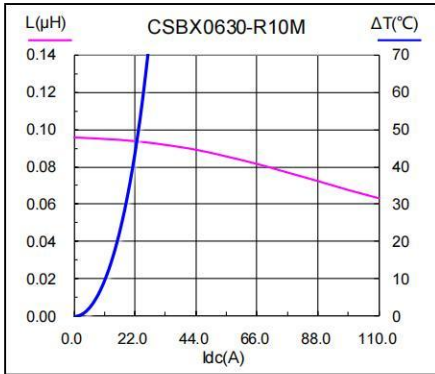
all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒：线路设计，组件布局，印刷线路板(PCB)尺寸及厚度，散热系统等均会影响产品温度。

请务必在最终应用时，验证产品发热状况。



6 Saturation Current vs Temperature Rise Current Curve 饱和电流 vs 温升电流曲线



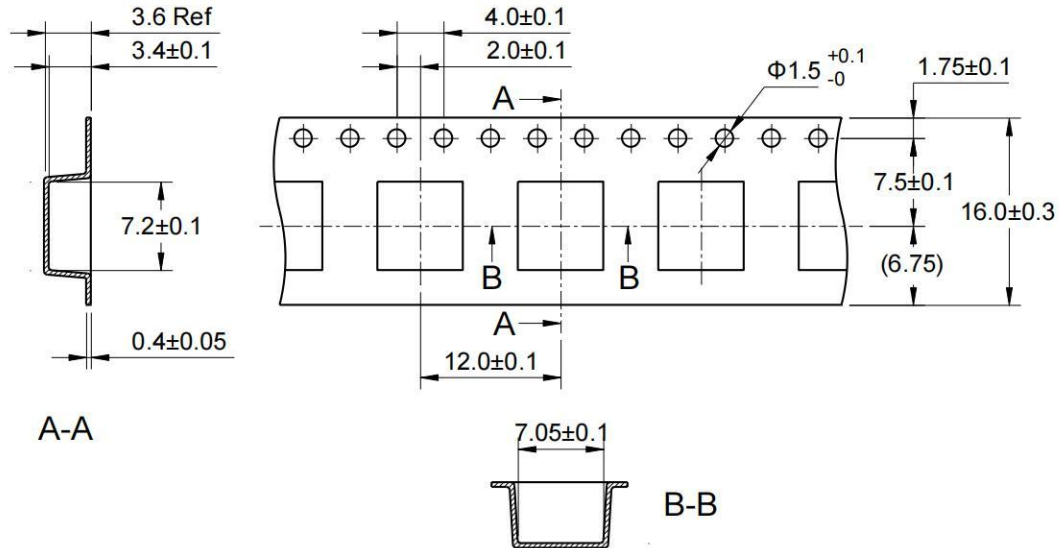


7 Packing Specification

包装规格

7.1 Carrier Tape Dimensions (mm)

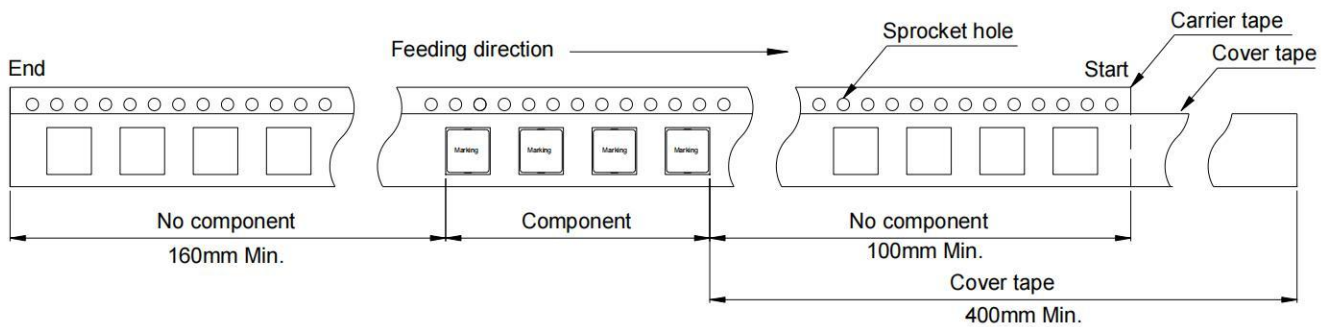
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape Direction

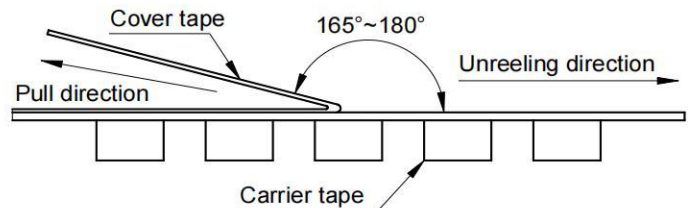
捆包方向



7.3 Cover Tape Peel Off Condition

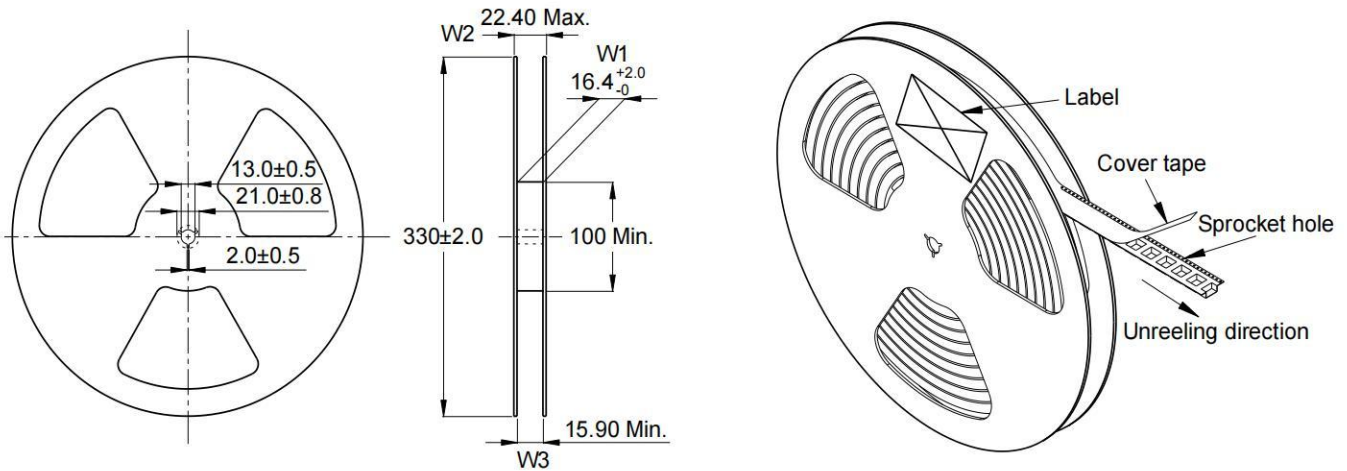
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1 ~ 1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。





7.4 Reel Dimensions (mm)
卷盘尺寸



7.5 Carton Dimensions and Packing Quantity
包装箱尺寸和包装数量

■ Inner Carton : 340×340×95mm
内包装盒

■ Out Carton : 360×360×370mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSBX0630	1500pcs	(1500×3) = 4500pcs	(4500×3) = 13500pcs

7.6 Label Making
标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label 产品标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

Shipping Label 运输标签
■ Packing No. 包装流水号
■ Quantity 数量
■ Shipment Date 出货日期
■ Part No. 产品型号
■ Customer Part No. 客户型号
■ Customer Po No. 客户订单号

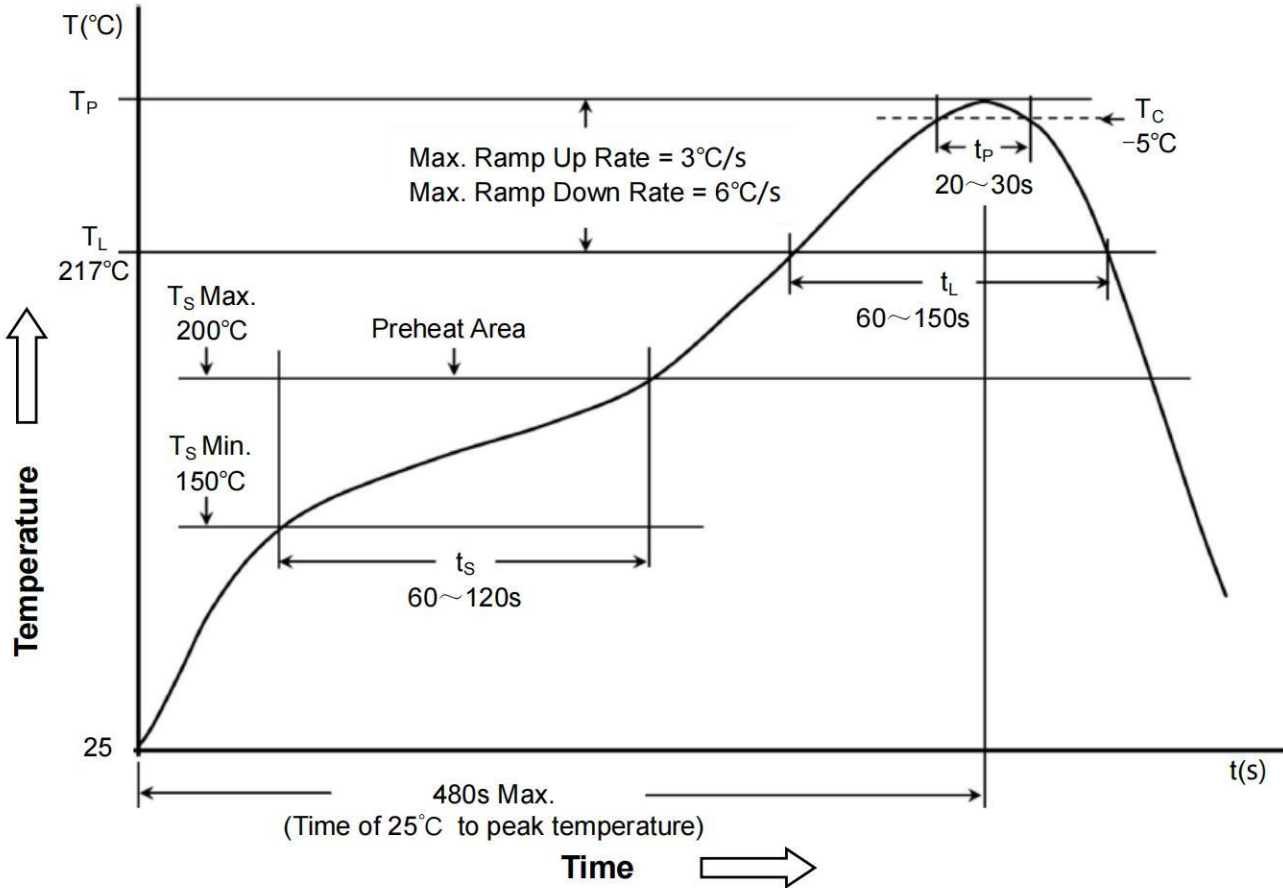


8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350 ~ 2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6 ~ 2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.

回流焊参照标准 IPC/JEDEC J-STD-020D.